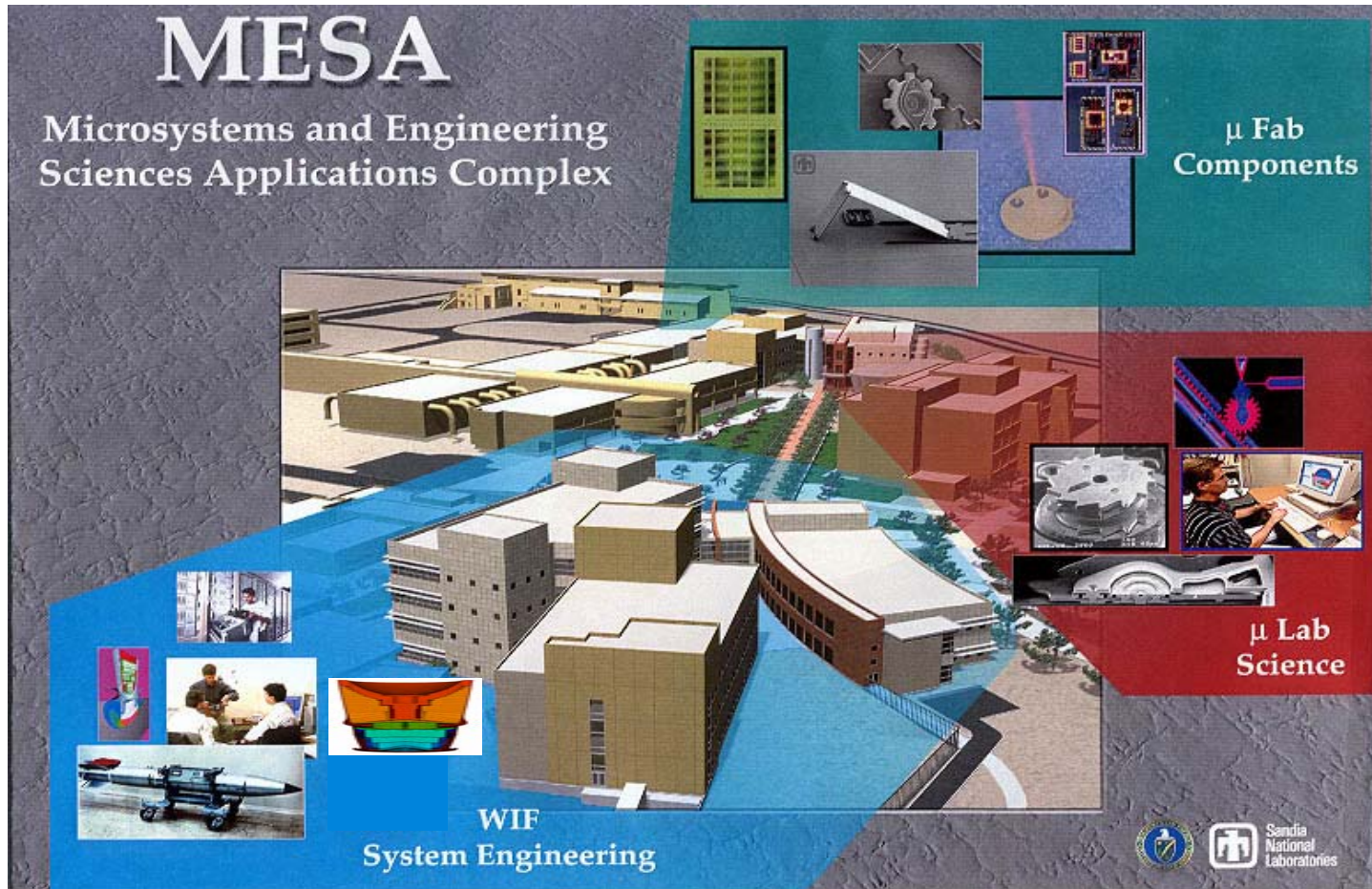


# MESA: A Government / University / Industry Partnership Opportunity for Microsystems



*Sandia is a Multiprogram Laboratory  
Operated by Sandia Corporation,  
a Lockheed Martin Company,  
for the United States Department of Energy  
Under Contract DE-ACO4-94AL85000.*

**Regan Stinnett, MESA Institute  
Sandia National Laboratories  
June 29, 2003**

# Sandia is a National Security Laboratory

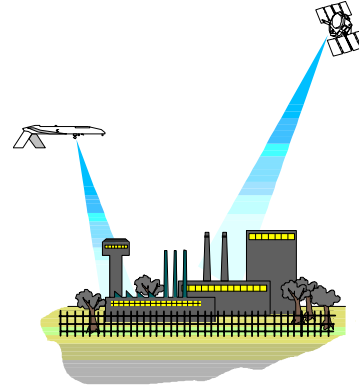
## Nuclear Weapons



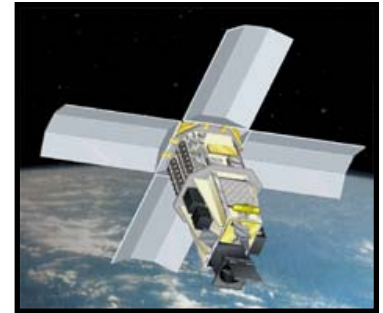
**Safe, Secure,  
Reliable Weapons**



## Nonproliferation & Materials Control



**Detection**



**Surveillance**

## Energy & Critical Resources



**Energy**



**Information**

**Transportation**



**Architectural  
Surety**

**DHS**

## Military Technologies & Applications

**Physical Security**

**Force/Facility  
Protection**



**Urban Operations**

**Military and anti- terrorism  
technologies**

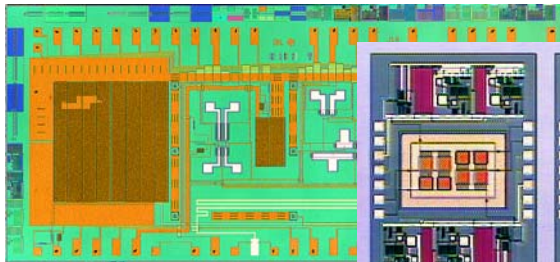
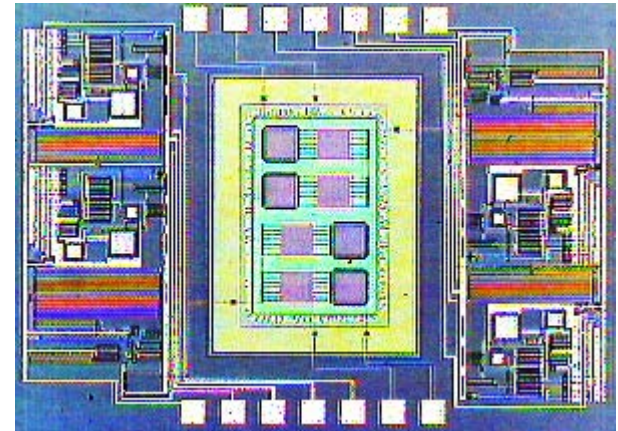


**Microsystems Technologies will be key in each of these areas**

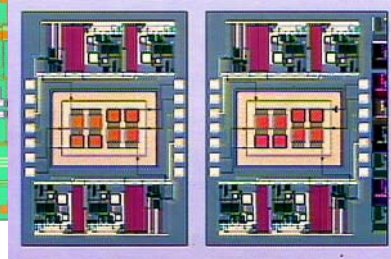


# Integrated Microsystems: The Next Technology Revolution

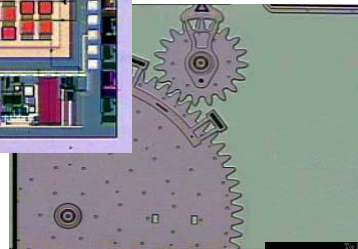
- The next leap in function of Integrated Circuits will involve more than just packing more transistors on the chip
- It will involve combining Si, III-V, MEMS, and advanced packaging technologies to create an integrated capability to :



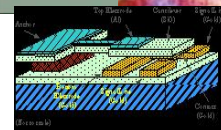
Sense  
(physical,  
environmental  
, imaging)



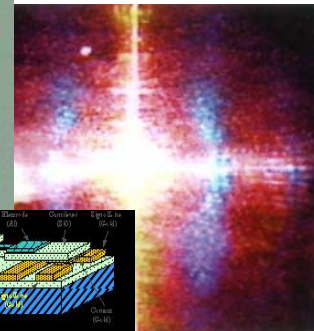
Decide  
(acquire,  
process,  
interpret)



Act  
(MEMS,  
microfluidics)



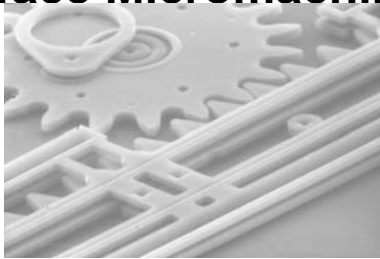
Communicate  
(optical, RF)



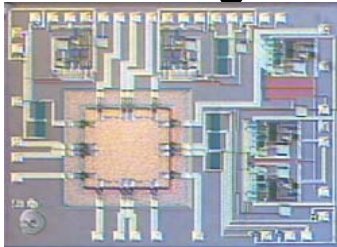
... affordably and reliably.

# Producing integrated microsystems requires a broad spectrum of capabilities

**Polysilicon  
Surface Micromachining**

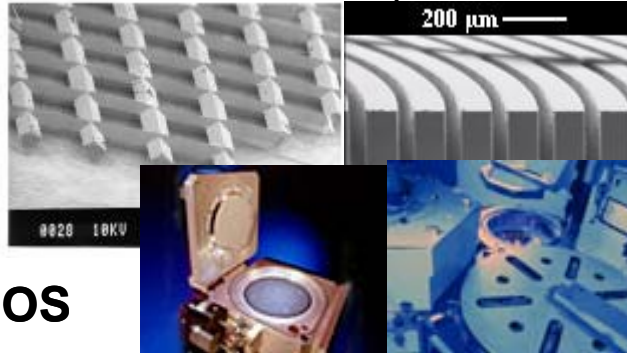


**Integrated Surface  
Micromachining and CMOS**

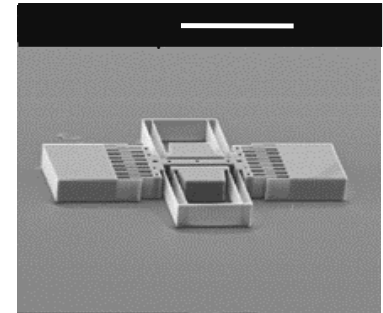


**Advanced  
Packaging**

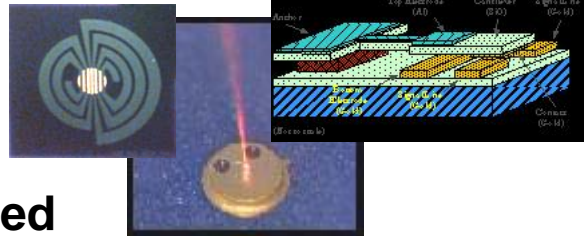
**Wet Chemistry  
Bulk Silicon Etching  
LPCVD, EPI**



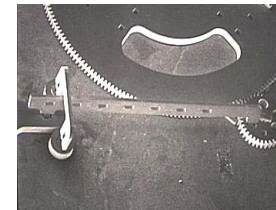
**High Aspect Ratio  
Silicon Etching (HARSE)**



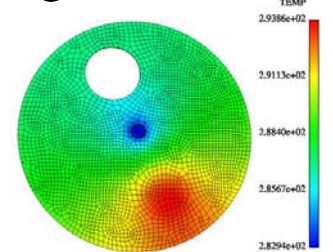
**III-V Compound Semiconductors**



**LIGA**



**Qualification**



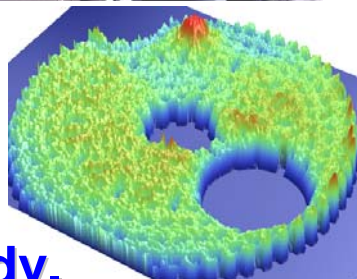
It is very difficult to obtain these capabilities  
**plus** the flexibility for R&D and prototyping.





# MESA provides complete facilities for microsystems design, integration, fabrication and testing

**\$463M including  
> 50% equipment  
and cleanrooms**



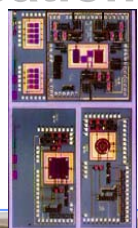
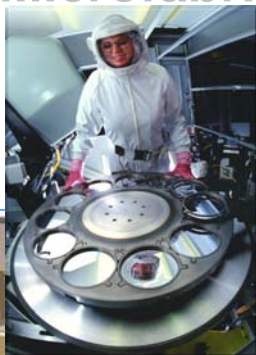
**Adv.  
computation**



**Packaging and  
qualification**



**Microfabrication**



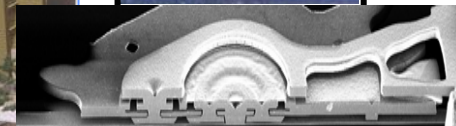
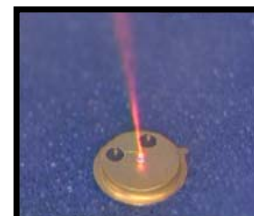
**Si Micromachining**



**Photonics**

**III-V**

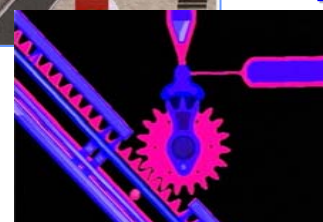
**Semiconductors**



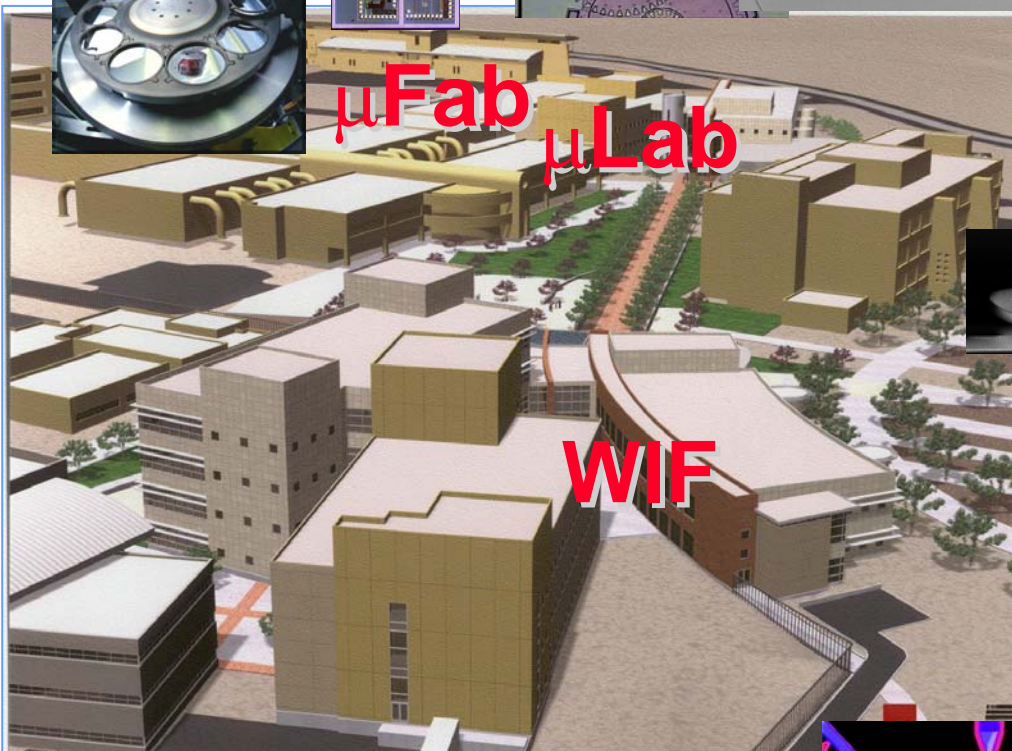
**Nanotechnology**



**3-D design,  
mod/sim**



**648 people  
391,000 sq ft**



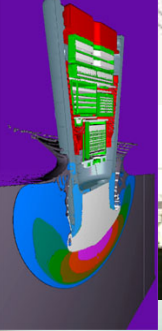


# Mesa Complex

# Components



## System Engineering

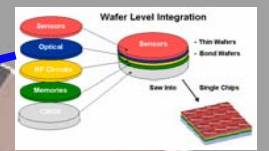
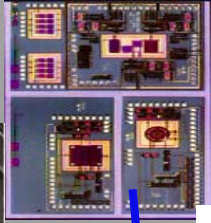


374 people  
162,000 GSF

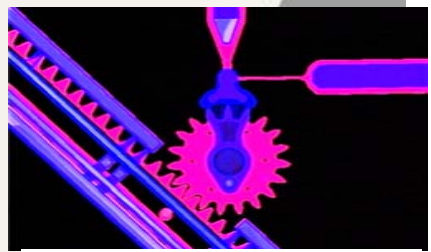
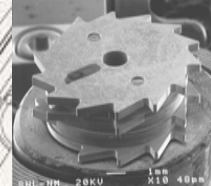
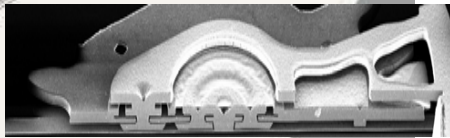
**TOTALS: Construction: \$246M, Equipment: \$168M  
Contingency: \$49M, TEC: \$463M**

98,000 GSF

## Packaging



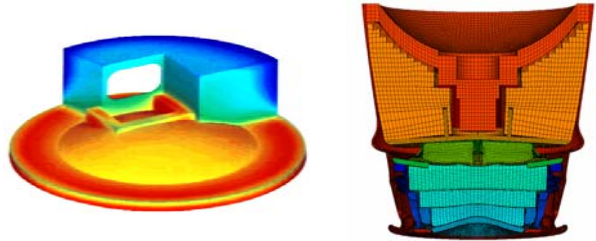
## Science



274 people  
131,000 GSF



# Sandia's computing resources are key elements of MESA



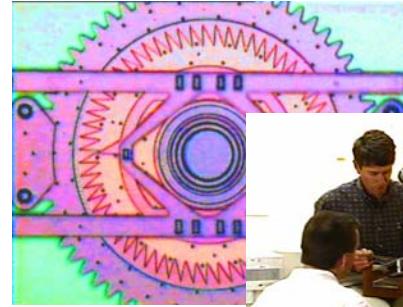
**JCEL - Algorithm & Code  
Development**

**High resolution  
3-D visualization**



**10 Gb/sec Desktop  
Connectivity**

**Production Computing  
3 T-ops → 20T-ops**



**Microsystems &  
components R&D**

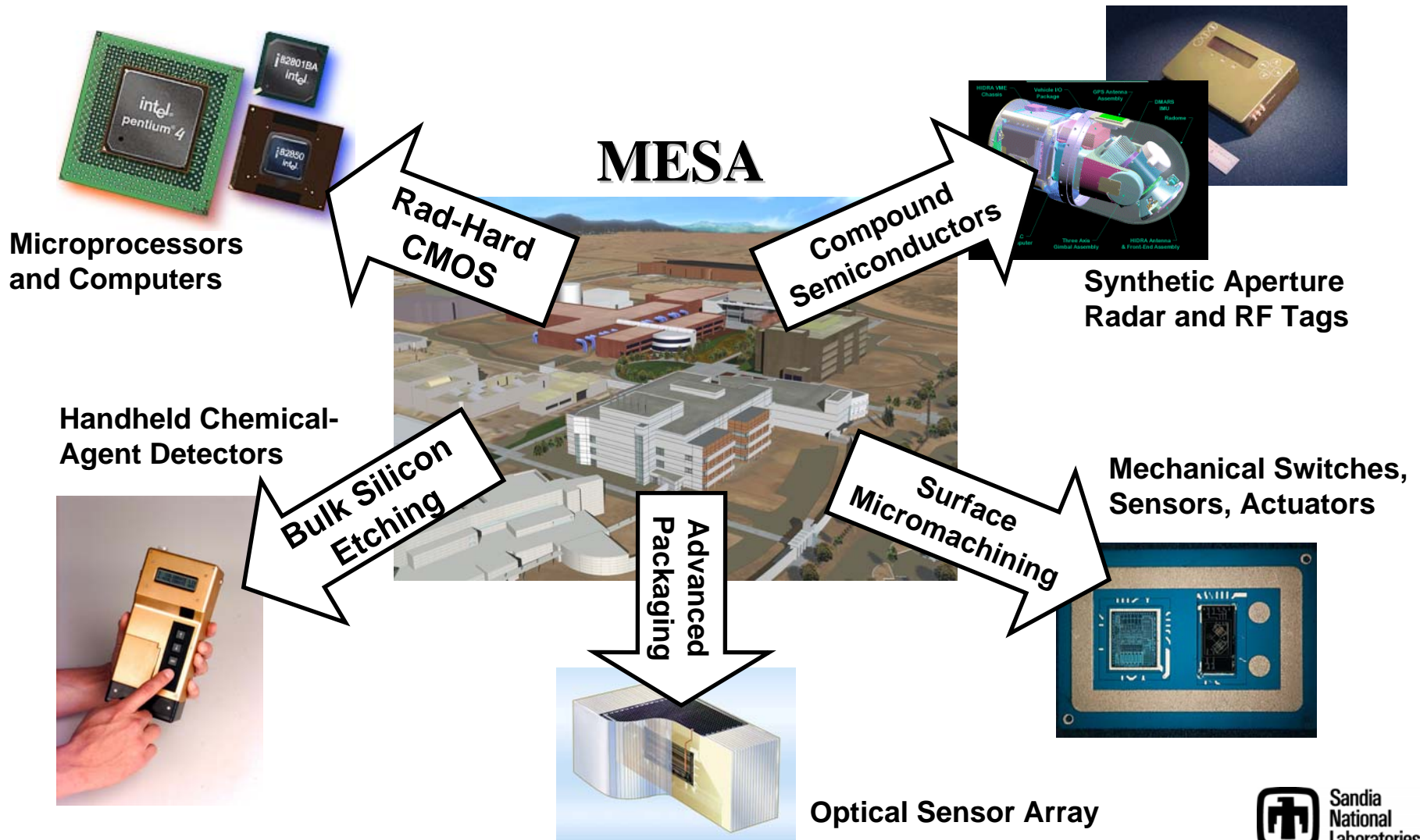


**Engineering  
& Analysis,  
Virtual  
Prototyping**



**Microsystems  
Process R&D**

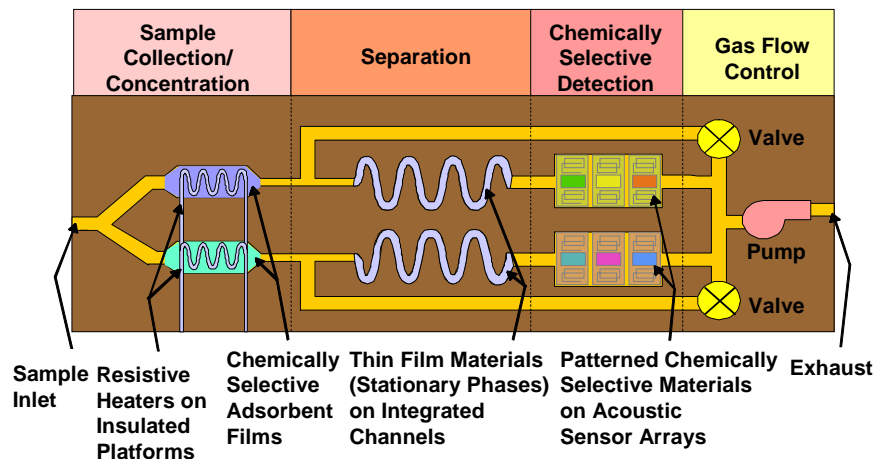
# Sandia Is Using MESA To Advance Microsystems Technologies Through Flagship Products





# **μChemLab™**

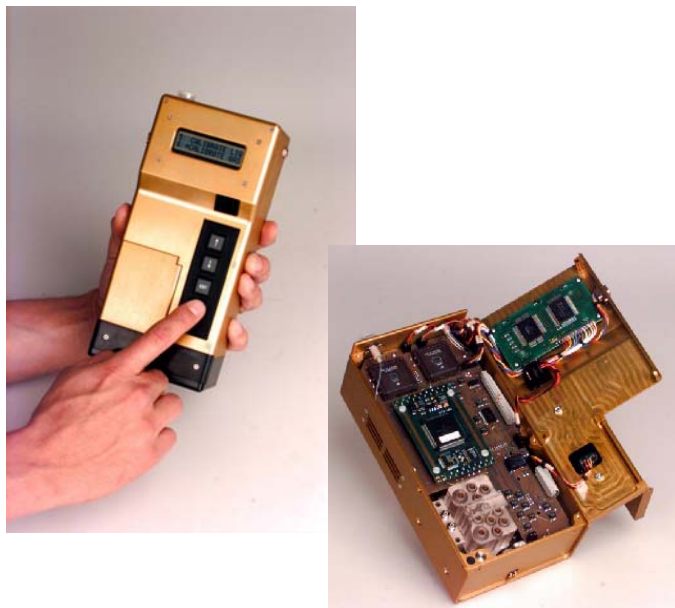
## **Handheld Chemical Analysis System**



- μChemLab system includes on-chip gas chromatograph with preconcentrator, separator column, and detectors
- Micromachined components enable miniaturization and rapid, low power response
- System has been assembled into a user-friendly hand-held unit

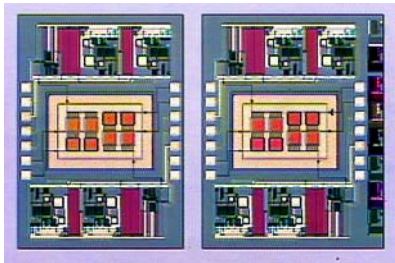
### **Applications:**

- CW and BW agent detection
- Explosive detection
- Environmental monitoring



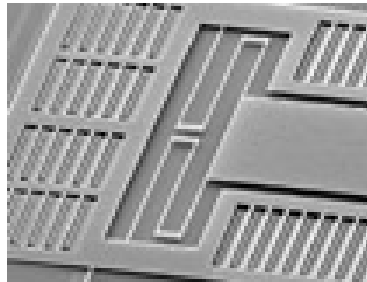
# But ...making Integrated Microsystems is difficult: e.g. MEMS

**Class I**  
*No Moving parts*



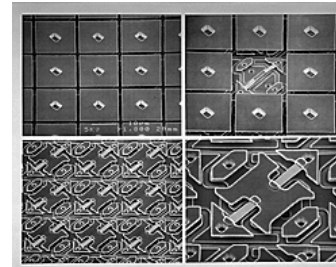
**Accelerometers**  
**Pressure Sensors**  
**Ink Jet Print Heads**  
**Strain Gauge**

**Class II**  
*Moving Parts, No  
Rubbing or  
Impacting Surfaces*



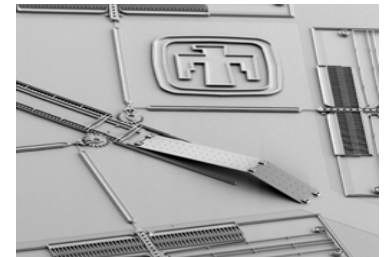
**Gyros**  
**Comb Drives**  
**Resonators**  
**Filters**

**Class III**  
*Moving Parts,  
Impacting  
Surfaces*



**TI DMD**  
**Relays**  
**Valves**  
**Pumps**

**Class IV**  
*Moving Parts,  
Impacting and  
Rubbing Surfaces*



**Optical Switches**  
**Corner Cube Refl.**  
**Shutters**  
**Scanners**  
**Locks**  
**Discriminators**

**(Successful Commercial Products in Blue)**

***Sandia needs strong partners to help us create  
more complex, integrated, and reliable devices***



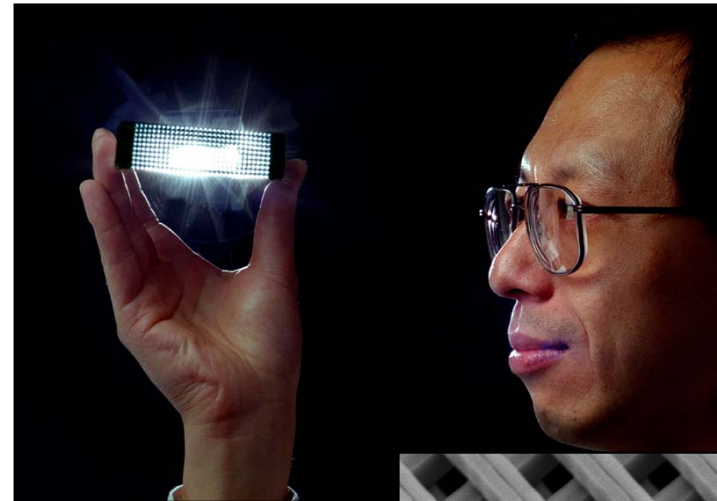
# Partnerships are vital to our work

**\$100 million annually in industry partnerships**

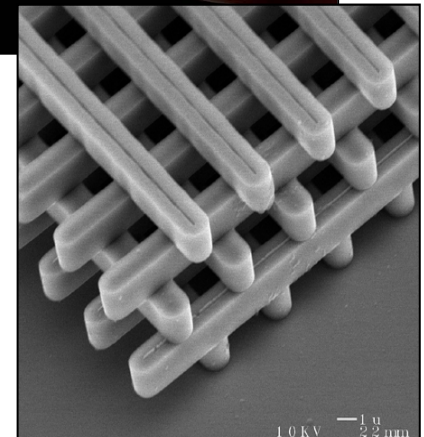


**Includes:**

Intel, Applied Materials, Fairchild, Motorola, EMCOR, MEMX ...



**More than 500 research projects with universities**



**Sandia has executed 516 CRADAs with industry partners in 42 states ... and 652 commercial licenses**



# Road to Deploy Microsystems in Weapons Goes Through Other Applications, Industry, & Universities

## Commercial Industry

- Telecomm, Bio-tech, RF...
- *Industrial Base*
- *Cost-effective solutions*

## Military and Non-Proliferation

- Nanosatellites, Battlefield Intelligence
- Chem/Bio/Radiation Sensors
- Micro-robotics, Navigation

## Weapons Applications

*assured reliability*

## Energy & Critical Resources

- Sub-surface monitoring at waste sites
- Seismic Sensors/oil expl.
- Photovoltaics, ...

University participation to create the talent pool and new ideas

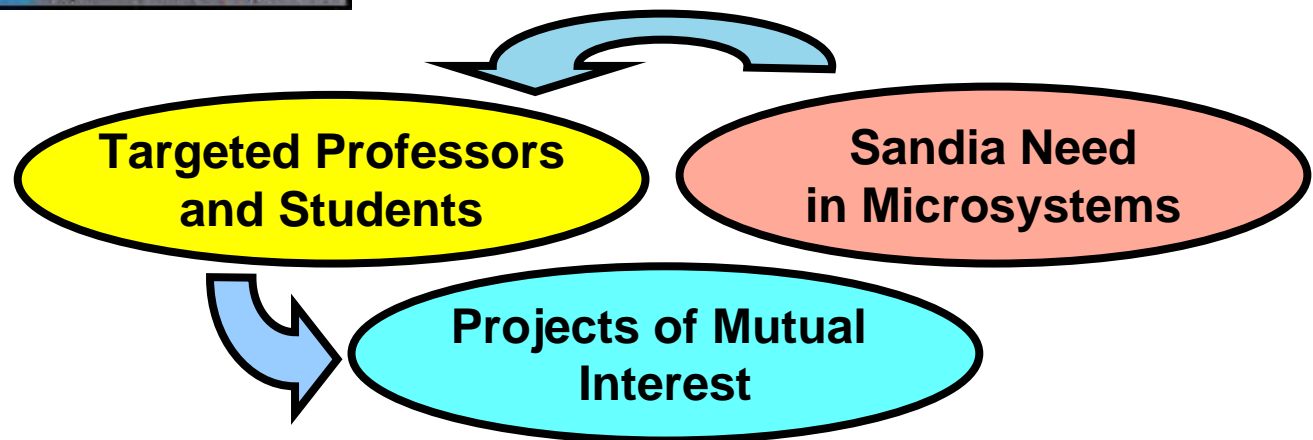


# The MESA Institute: Microsystems Partnerships with Universities



**Mission:** Develop key microsystems technologies while training top students on-site at Sandia's MESA facilities

**Approach:**





# **Students and Professors will Benefit from Participation**

---

- **Access to personnel, instruments, facilities, and capabilities not otherwise available**
  - Commercial facilities don't provide research flexibility
  - University facilities rarely have the full range of capabilities
- **Access to on-site research opportunities for students and professors, with costs paid by Sandia**
- **Exposure to “industry-like” microsystems environments**
- **Educational and employment opportunities for undergrad, graduate and postdoctoral students**
- **Joint proposals enabled by Sandia capabilities**





# The MESA Institute Program Has Three Tiers

---

## Characteristics

### Strategic University Partners

- Broad match to Sandia programs
- Interest from multiple line orgs and multiple faculty/disciplines
- Collaboration for joint programs

### University Partners

- Specific faculty expertise needed by line orgs
- Top graduate students
- Microsystems courses

### Educational Infrastructure

- Tech/Voc Inst.
- Faculty training

**Strategic  
University  
Partners**

**Specific Professors  
and their students**

**Infrastructure Orgs**

## Goals

- Leverage Sandia & Univ programs
- Long term pipeline for new hires
- Joint programs w/ 3<sup>rd</sup> party funding

- Leverage line org program
- Top new hires in key areas
- Long term faculty relations

- Technologist availability
- Long term tech pipeline

Each type of partnership is important to Sandia!

# To Maximize the Benefit of MESA to the Nation Sandia Needs Long Term Partners



## Partners should be:

- Working in microtechnology / nano-science areas of interest to Sandia
- Have interdisciplinary microsystems programs of national stature
- Committed to significant investment in their own microsystems programs
- Willing to give Sandia interests high priority

## Sandia offers its partners:

- Long term collaborative relationships with Sandia organizations
- Access to Sandia's world class facilities
- Fellowships for top students, and professors in microsystems and related nano science areas to work on-site at Sandia
- Support for joint proposals to federal agencies (eg. DOE, NSF, NIH,...)





# **MESA Institute Process - Overview**

---

- **Process initiated by Sandia staff, professor and student**
- **Graduate and undergraduate students (U.S. citizens)**
- **Negotiated on-site assignments of 2 to 24 months**
  - Participating professor provides research guidance
  - Designated Sandia staff provides on-site supervision/mentoring
- **Microsystems projects of mutual interest to Sandia, professor, and student**
  - 3 page proposals reviewed by MESA Institute panel within 6 weeks
  - MESA Institute funds student labor, travel, plus professor visits
  - Sandia provides facilities, work space, processing



# Sandia Points of Contact

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## General Information

Regan Stinnett (505) 284-4841 [rwstinn@sandia.gov](mailto:rwstinn@sandia.gov)

## Cooperative agreements and I.P.

Paul Smith (505) 843-4146 [SMITHPM@sandia.gov](mailto:SMITHPM@sandia.gov)

## MEMS Fabrication

Tom Zipperian (505) 844-6407 [tezippe@sandia.gov](mailto:tezippe@sandia.gov)

## RF and Opto Microsystems

Dave Palmer (505) 844-2138 [palmerdw@sandia.gov](mailto:palmerdw@sandia.gov)

## Microsensors

Steve Martin (505) 844-9723 [sjmarti@sandia.gov](mailto:sjmarti@sandia.gov)

## Photonics & Compound Semiconductor Fabrication

Charles Sullivan (505) 844-9254 [ctsulli@sandia.gov](mailto:ctsulli@sandia.gov)

Peter Esherick (505) 844-5857 [esheric@sandia.gov](mailto:esheric@sandia.gov)

## LIGA

Jill Hruby (925) 294-2596 [jmhruby@sandia.gov](mailto:jmhruby@sandia.gov)

Craig Henderson (925) 294-3628 [cchende@sandia.gov](mailto:cchende@sandia.gov)

Todd Christenson (505) 844-0649 [trchris@sandia.gov](mailto:trchris@sandia.gov)

## Packaging

Thom Fischer (505) 844-8966 [tafisch@sandia.gov](mailto:tafisch@sandia.gov)

## Intelligent Micromachines

Jay Jakubczak (505) 844-9196 [jayj@sandia.gov](mailto:jayj@sandia.gov)

## MEMS Design and Applications

David Plummer (505) 845-9564 [dwplumm@sandia.gov](mailto:dwplumm@sandia.gov)

Jay Jakubczak (505) 844-9196 [jayj@sandia.gov](mailto:jayj@sandia.gov)

Gerard Sleaf (505) 844-2195 [gesleaf@sandia.gov](mailto:gesleaf@sandia.gov)

## Computationally Enabled Design

Steven Kempka (505) 844-8918 [snkempk@sandia.gov](mailto:snkempk@sandia.gov)

## Microsystems Reliability

Fred Sexton (505) 844-3927 [sextonfw@sandia.gov](mailto:sextonfw@sandia.gov)

## Microsystems Failure Analysis

Richard Anderson (505) 844-3274 [andersre@sandia.gov](mailto:andersre@sandia.gov)

## Surface Science and Nanotechnology

Will Gauster (505) 284-3504 [wbgauster@sandia.gov](mailto:wbgauster@sandia.gov)

MESA Institute Web Page: <http://mesa.sandia.gov/institute/institute.htm>





# **Summary: MESA Is Creating ...**

---

- **Advanced facilities and capabilities to meet national needs for microsystems R&D, design, and prototyping**
- **Co-located multi-disciplinary teams**
  - **Microsystems (microelectronics, MEMS, III-V, packaging)**
  - **Computation and simulation**
  - **Materials science**
  - **Systems design and integration**
  - **including government, academic, and industrial partners**
- **Opportunities for students and professors to participate in leading edge microsystems research in areas of national interest**
- **Opportunities for government and industry partnerships to take technology from R&D to use in national security applications**
- **Value Proposition for Partners**
  - **access unique microsystems R&D and prototyping facilities through collaboration with Sandia organizations on joint projects of mutual interest**
  - **cost of work is leveraged by \$1B investment in capital facilities and capabilities**

# MESA Needs You Too!

U. Michigan  
UC Berkeley  
U. Oklahoma  
U. Colorado  
Georgia Tech  
AF Inst. Of T

Arizona State  
U. Florida  
U. Wisconsin  
U. Missouri-R  
U. New Mexico  
Rochester Inst. T.  
Florida State U.



Purdue U.  
U. Arizona  
Texas Tech  
NJ Inst.Tech.  
Univ. of Pacific  
Texas A&M

UCLA  
NM State U.  
U. Arkansas  
U. Minnesota  
Kettering Inst  
U. Of Illinois  
MIT

*41 students from 26 universities, to 20 Sandia orgs in FY03*



Sandia is a multiprogram laboratory operated by Sandia Corporation, a Lockheed Martin Company, for the United States Department of Energy under contract DE-AC04-94AL85000.

